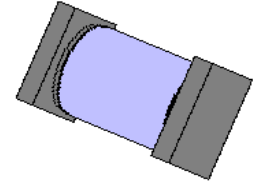


**DESCRIPTION**

This "fast recovery" surface mount rectifier diode series is military qualified to MIL-PRF-19500/429 and is ideal for high-reliability applications where a failure cannot be tolerated. These industry-recognized 1.0 Amp rated rectifiers for working peak reverse voltages from 200 to 1000 volts are hermetically sealed with voidless-glass construction using an internal "Category I" metallurgical bond. These devices are also available in axial-leaded package configurations for thru-hole mounting (see separate data sheet for 1N5615 thru 1N5623). Microsemi also offers numerous other rectifier products to meet higher and lower current ratings with various recovery time speed requirements including fast and ultrafast device types in both through-hole and surface mount packages.

**IMPORTANT:** For the most current data, consult MICROSEMI's website: <http://www.microsemi.com>

**APPEARANCE**



**Package "A"  
or D-5A**

**FEATURES**

- Surface mount package series equivalent to the JEDEC registered 1N5615 to 1N5623 series
- Voidless hermetically sealed glass package
- Triple-Layer Passivation
- Internal "Category I" Metallurgical bonds
- Working Peak Reverse Voltage 200 to 1000 Volts.
- JAN, JANTX, JANTXV, and JANS available per MIL-PRF-19500/429
- Axial-leaded equivalents also available (see separate data sheet for 1N5615 thru 1N5623)

**APPLICATIONS / BENEFITS**

- Fast recovery 1 Amp rectifiers 200 to 1000 V
- Military and other high-reliability applications
- General rectifier applications including bridges, half-bridges, catch diodes, etc.
- High forward surge current capability
- Extremely robust construction
- Low thermal resistance
- Controlled avalanche with peak reverse power capability
- Inherently radiation hard as described in Microsemi MicroNote 050

**MAXIMUM RATINGS**

- Junction & Storage Temperature: -65°C to +175°C
- Thermal Resistance: 13°C/W junction to end cap
- Thermal Impedance: 4.5°C/W @ 10 ms heating time
- Average Rectified Forward Current (I<sub>O</sub>): 1.0 Amps @ T<sub>A</sub> = 55°C
- Forward Surge Current: 30 Amps @ 8.3 ms half-sine
- Solder Temperatures: 260°C for 10 s (maximum)

**MECHANICAL AND PACKAGING**

- CASE: Hermetically sealed voidless hard glass with Tungsten slugs
- TERMINATIONS: End caps are Copper with Tin/Lead (Sn/Pb) finish. Note: Previous inventory had solid Silver end caps with Tin/Lead (Sn/Pb) finish.
- MARKING & POLARITY: Cathode band only
- TAPE & REEL option: Standard per EIA-481-B
- WEIGHT: 193 mg
- See package dimensions and recommended pad layout on last page

**ELECTRICAL CHARACTERISTICS**

TYPE	WORKING PEAK REVERSE VOLTAGE V <sub>RWM</sub>	MINIMUM BREAKDOWN VOLTAGE V <sub>BR</sub> @ 50µA	AVERAGE RECTIFIED CURRENT I <sub>O</sub> @ T <sub>A</sub> (NOTE 1)		FORWARD VOLTAGE (MAX.) V <sub>F</sub> @ 3A	REVERSE CURRENT (MAX.) I <sub>R</sub> @ V <sub>RWM</sub>		CAPACITANCE (MAX.) C @ V <sub>R</sub> =12 V f=1 MHz	MAXIMUM SURGE CURRENT I <sub>FSM</sub> (NOTE 2)	REVERSE RECOVERY (MAX.) (NOTE 3) t <sub>rr</sub>
			AMPS			µA				
			50°C	100°C		25°C	100°C			
1N5615US	200	220	1.00	.750	.8 MIN.	.5	25	45	25	150
1N5617US	400	440	1.00	.750		.5	25	35	25	150
1N5619US	600	660	1.00	.750		.5	25	25	25	250
1N5621US	800	880	1.00	.750	1.6	.5	25	20	25	300
1N5623US	1000	1100	1.00	.750	MAX.	.5	25	15	25	500

**NOTE 1:** From 1 Amp at T<sub>A</sub> = 55°C, derate linearly at 5.56 mA/°C to 0.75 Amp at T<sub>A</sub> = 100°C. From T<sub>A</sub> = 100°C, derate linearly at 7.5 mA/°C to 0 Amps at T<sub>A</sub> = 200°C. These ambient ratings are for PC boards where thermal resistance from mounting point to ambient is sufficiently controlled where T<sub>J(max)</sub> does not exceed 175°C.

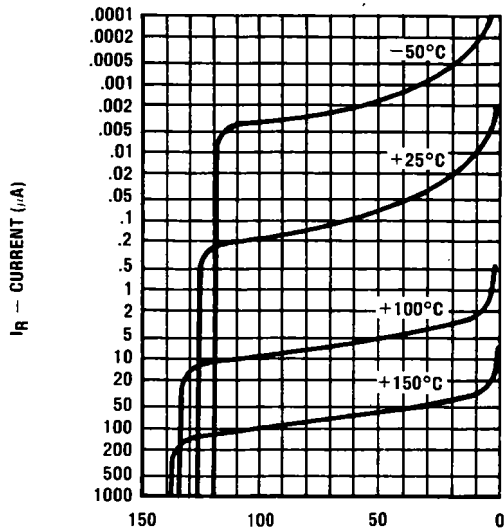
**NOTE 2:** T<sub>A</sub> = 100°C, f = 60 Hz, I<sub>O</sub> = 750 mA for ten 8.3 ms surges @ 1 minute intervals

**NOTE 3:** I<sub>F</sub> = 0.5A, I<sub>RM</sub> = 1A, I<sub>R(REC)</sub> = 0.250 A

**SYMBOLS & DEFINITIONS**

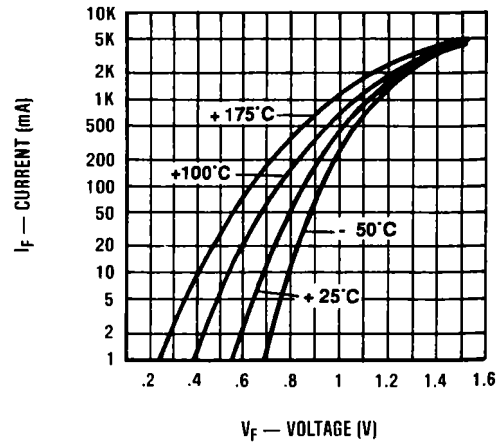
Symbol	Definition
$V_{BR}$	Minimum Breakdown Voltage: The minimum voltage the device will exhibit at a specified current
$V_{RWM}$	Working Peak Reverse Voltage: The maximum peak voltage that can be applied over the operating temperature range
$I_O$	Average Rectified Output Current: Output Current averaged over a full cycle with a 50 hZ or 60 Hz sine-wave input and a 180 degree conduction angle
$V_F$	Maximum Forward Voltage: The maximum forward voltage the device will exhibit at a specified current
$I_R$	Maximum Leakage Current: The maximum leakage current that will flow at the specified voltage and temperature
C	Capacitance: The capacitance in pF at a frequency of 1 MHz and specified voltage
$t_{rr}$	Reverse Recovery Time: The time interval between the instant the current passes through zero when changing from the forward direction to the reverse direction and a specified decay point after a peak reverse current occurs.

**GRAPHS**



**FIGURE 1**

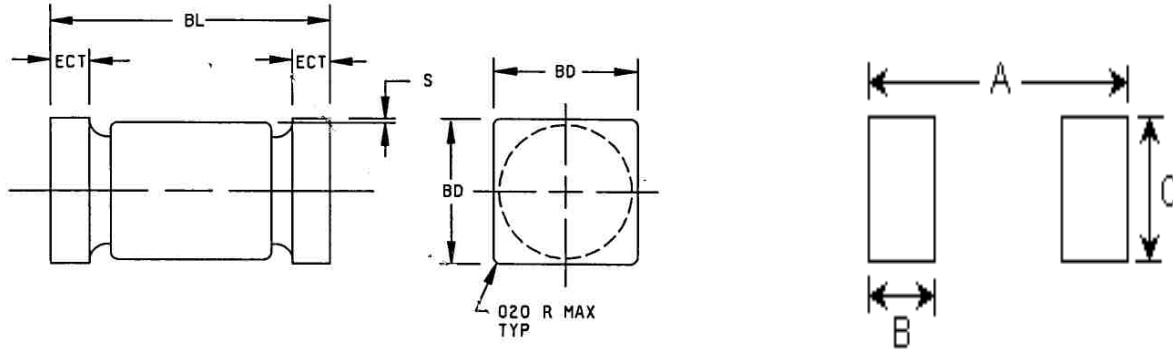
TYPICAL REVERSE CURRENT vs  $V_R$



**FIGURE 2**

TYPICAL FORWARD VOLTAGE vs FORWARD CURRENT

**PACKAGE DIMENSIONS AND PAD LAYOUT**



NOTE: This Package Outline has also previously been identified as "D-5A"

	INCHES		mm	
	MIN	MAX	MIN	MAX
<b>BD</b>	.097	.103	2.46	2.62
<b>BL</b>	.185	.200	4.70	5.08
<b>ECT</b>	.019	.028	0.48	0.71
<b>S</b>	.003	---	0.08	---

**PAD LAYOUT**

	INCHES	mm
<b>A</b>	0.246	6.25
<b>B</b>	0.067	1.70
<b>C</b>	0.105	2.67

Note: If mounting requires adhesive separate from the solder, an additional 0.060 inch diameter contact may be placed in the center between the pads as an optional spot for cement.